



SPECIFICATION FOR APPROVAL

CUSTOMER			
NOMINAL FREQUENCY	24.000000 MHz		
PRODUCT TYPE	TYPE FL 3.2x2.5 SEAM SEALED CRYSTAL		
SPEC. NO. (P/N)	FL2400271Q		
CUSTOMER P/N			
ISSUE DATE	May 13, 2021		
VERSION	A		

APPROVED	PREPARED	QA
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- *Pb-free
- *RoHS Compliant
- *HF-Halogen Free
- *REACH Compliant
- *AEC-Q200 Compliant

E0-R-4-014 Rev. F Page i

TYPE FL 3.2x2.5 SEAM SEALED CRYSTAL FL2400271Q

VER. A 13-May-21

VERSION HISTORY

Version No.	Version Date	Description	Notes
Α	May.13,2021	Initial Release	



E0-R-4-014 Rev. F

FL2400271Q

VER. A 13-May-21

ELECTRICAL SPECIFICATIONS

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	24.000000	MHz	
Mode of Oscillation	MO	AT Cut-Fundamental		
Calibration Load Capacitance	CL	12	pF	
Calibration Tolerance	FL	±10	ppm	at 25℃±3℃
Operating Temperature Range	TR	-40 to +125	C.	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±50	ppm	Reference to the Frequency at 25℃
Operating Drive Level		10	μW	
Maximum Drive Level		300	μW	
Equivalent Series Resistance	ESR	50	Ω	Max
Shunt Capacitance	C0	5	pF	Max
Aging at 25℃		±3	ppm	Max, 1st year
Storage Temperature		-55 to +125	.C	
Insulation Resistance		500	МΩ	Min

★ This product doesn't include harmful substance that stipulated by SONY SS-00259 Level 1 and S-AT2-001 Level 1 standard. RoHS Compliant (Pb - Free).



E0-R-4-014 Rev. F Page 1

FL2400271Q

VER. A 13-May-21

AEC-Q200 RELIABILITY TEST SPECIFICATIONS:

1. Initial

1.1 Physical Dimensions: JESD22, Method JB1-100

1.2 External Visual: MIL-STD-883, Method 2009

1.3 Freq. Vs. Temperature: Per Specification/Datasheet

2. Mechanical

2.1 Mechanical Shock: MIL-STD-202 Method 213

2.2 Vibration: MIL-STD-202 Method 204

2.3 Solderability: J-STD-002

2.4 Board Flex: AEC Q200-005

3.Environmental

3.1 Temperature Cycle: JESD22, Method JA-104

3.2 Resistance to Solder Heat: MIL-STD-202 Method 210

3.3 High Temperature Operating Life: MIL-STD-202, Method 108

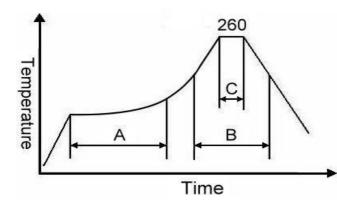
3.4 High Temperature Exposure: MIL-STD-202, Method 108

3.5 High Temperature & High Humidity: MIL-STD-202, Method 103

3.6 Thermal Shock: MIL-STD-202, Method 107

SUGGESTED IR REFLOW PROFILE

*As per IPC-JEDEC J-STD-020D



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13	U	ıc	•

	Stage	Temperature	Time
Α	Preheat	150~200°C	60~120 Sec
В	Primary Heat	217°C	60~150 Sec
С	Peak	260°C	10 Sec

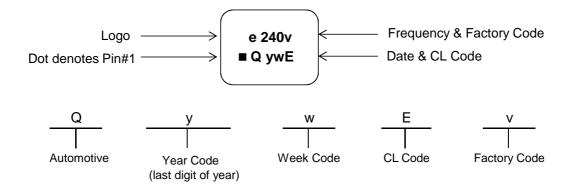


E0-R-4-014 Rev. F Page 2

FL2400271Q

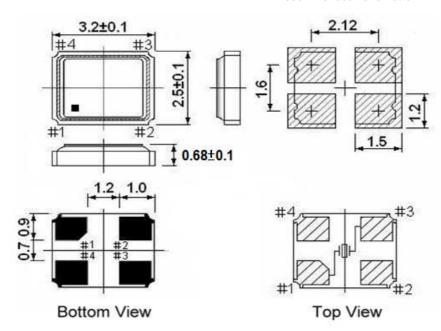
VER. A 13-May-21

MARKING



MECHANICAL DRAWINGS (Scale: None. Dimensions are in mm.)

Recommended Land Pattern



** Recommended - Pin 1 & 3 : CRYSTAL Pin 2 & 4 : GND

Notes:

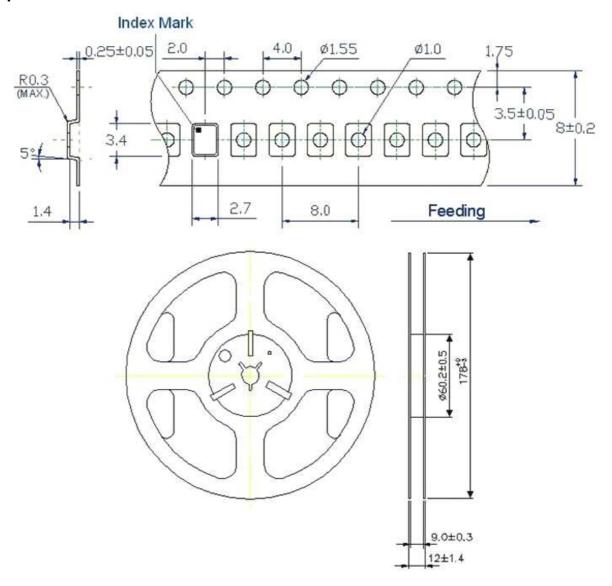
- Package drawings are for reference only, and the appearances of objects may vary.
 Actual packages are based on the real product.
- 2. The marking dot denotes Pin#1.
- 3. The position and shape of the chamfer pin may vary and are based on the real product.

E0-R-4-014 Rev. F

FL2400271Q

VER. A 13-May-21

Tape & Reel



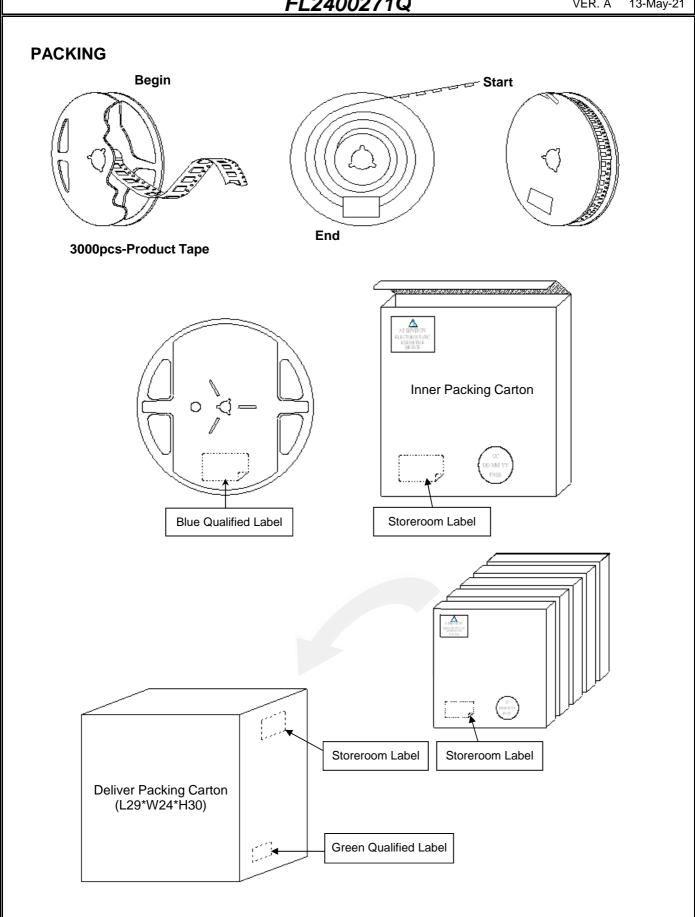
- 1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
- 2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

DECDES.

E0-R-4-014 Rev. F Page 4

FL2400271Q

VER. A 13-May-21





E0-R-4-014 Rev. F Page 5